

APPARATUS AND METHOD FOR SPLITTING SUBSTRATES

ABSTRACT

5 The invention provides an apparatus for splitting a substrate apart, the substrate comprising two adjoining wafers defining between them a cleavage plane, the apparatus being characterized in that it comprises:

10 - means for feeding splitter means with a plurality of substrates disposed in a substrate-storage direction;

 - splitter means for splitting apart the wafers of the substrates, the splitter means comprising moving jaws; and

15 - means for performing controlled displacement of certain substrate wafers after they have been split apart in a direction that is substantially parallel to the substrate-storage direction,

 whereby the apparatus is suitable for splitting apart the plurality of substrates.

20 The invention also provides an associated splitting method.